

Important notice

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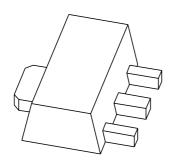
If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS

DATA SHEET



BSR30; BSR31; BSR33 PNP medium power transistors

Product data sheet Supersedes data of 1999 Apr 26 2004 Dec 13



PNP medium power transistors

BSR30; **BSR31**; **BSR33**

FEATURES

- High current (max. 1 A)
- Low voltage (max. 80 V).

APPLICATIONS

- Telephony and general industrial applications
- · Thick and thin-film circuits.

DESCRIPTION

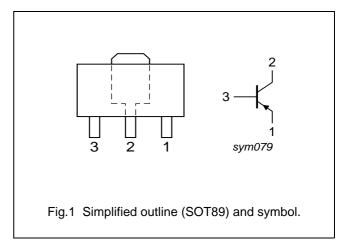
PNP medium power transistor in a SOT89 plastic package. NPN complements: BSR40; BSR41 and BSR43.

MARKING

TYPE NUMBER	MARKING CODE
BSR30	BR1
BSR31	BR2
BSR33	BR4

PINNING

PIN	DESCRIPTION
1	emitter
2	collector
3	base



ORDERING INFORMATION

TYPE NUMBER	PACKAGE				
TIPE NUMBER	NAME	NAME DESCRIPTION VERSION			
BSR30	SC-62	C-62 plastic surface mounted package; collector pad for good heat transfer; 3 leads			
BSR31					
BSR33					

PNP medium power transistors

BSR30; BSR31; BSR33

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter			
	BSR30; BSR31		_	-70	V
	BSR33		_	-90	V
V _{CEO}	collector-emitter voltage	open base			
	BSR30; BSR31		_	-60	V
	BSR33		_	-80	V
V _{EBO}	emitter-base voltage	open collector	_	- 5	V
I _C	collector current (DC)		-	-1	Α
I _{CM}	peak collector current		_	-2	Α
I _{BM}	peak base current		-	-200	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	-	1.35	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	ambient temperature		-65	+150	°C

Note

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	93	K/W
R _{th(j-s)}	thermal resistance from junction to soldering point		13	K/W

Note

1. Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 6 cm². For other mounting conditions, see "Thermal considerations for SOT89 in the General Part of associated Handbook".

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PNP medium power transistors

BSR30; BSR31; BSR33

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	I _E = 0 A; V _{CB} = -60 V	-	-100	nA
		$I_E = 0 \text{ A}; V_{CB} = -60 \text{ V}; T_j = 150 ^{\circ}\text{C}$	_	-50	μΑ
I _{EBO}	emitter-base cut-off current	I _C = 0 A; V _{EB} = -5 V	_	-100	nA
h _{FE}	DC current gain	$I_C = -100 \mu A; V_{CE} = -5 V; \text{ note } 1$			
	BSR30		10	_	
	BSR31; BSR33		30	_	
	DC current gain	$I_C = -100 \text{ mA}; V_{CE} = -5 \text{ V}; \text{ note 1}$			
	BSR30		40	120	
	BSR31; BSR33		100	300	
	DC current gain	$I_C = -500 \text{ mA}; V_{CE} = -5 \text{ V}; \text{ note 1}$			
	BSR30		30	_	
	BSR31; BSR33		50	_	
V _{CEsat}	collector-emitter saturation	$I_C = -150 \text{ mA}; I_B = -15 \text{ mA}; \text{ note } 1$	_	-0.25	V
	voltage	$I_C = -500 \text{ mA}$; $I_B = -50 \text{ mA}$; note 1	_	-0.5	V
V _{BEsat}	base-emitter saturation voltage	$I_C = -150 \text{ mA}$; $I_B = -15 \text{ mA}$; note 1	_	-1	V
		$I_C = -500 \text{ mA}$; $I_B = -50 \text{ mA}$; note 1	_	-1.2	V
f _T	transition frequency	I _C = -50 mA; V _{CE} = -10 V; f = 100 MHz	100	_	MHz

Note

1. Pulse test: t_p = 300 μ s; δ < 0.01.

2004 Dec 13

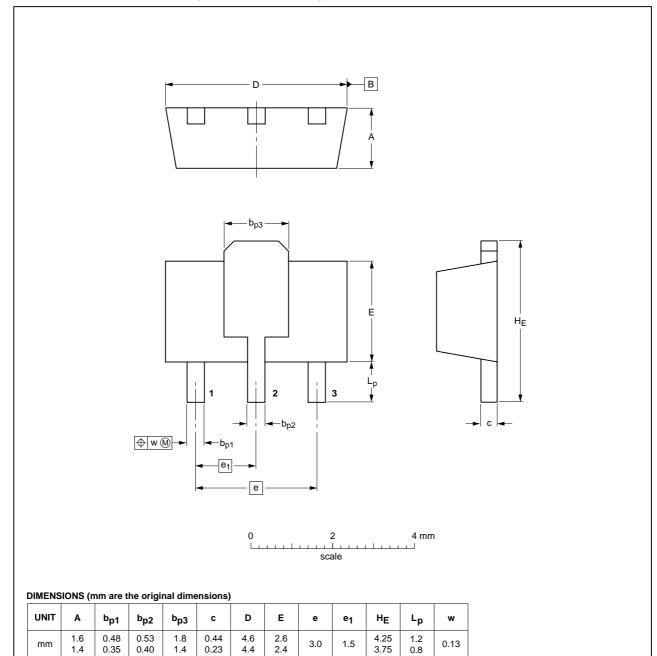
PNP medium power transistors

BSR30; BSR31; BSR33

PACKAGE OUTLINE

Plastic surface-mounted package; collector pad for good heat transfer; 3 leads

SOT89



OUTLINE	ITLINE REFERENCES		EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT89		TO-243	SC-62			04-08-03 06-03-16

PNP medium power transistors

BSR30; BSR31; BSR33

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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- 2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: http://www.nxp.com
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